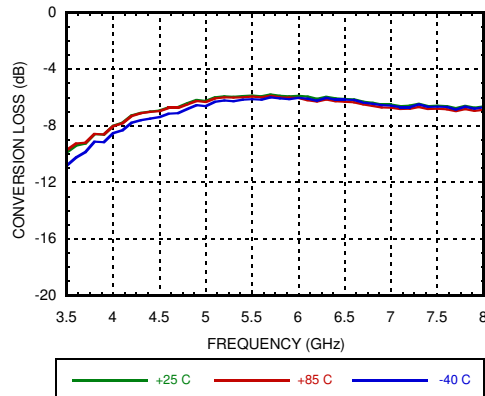


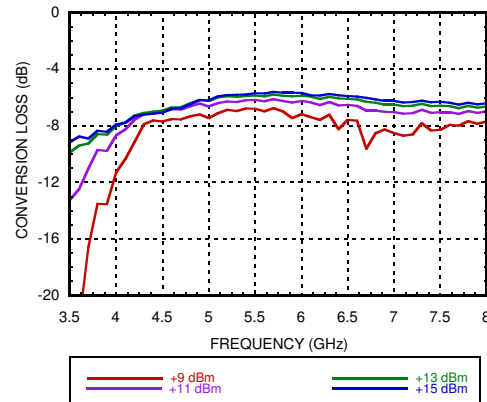
GaAs MMIC DOUBLE-BALANCED MIXER 3.5 - 8 GHz

High Side LO, Down-converter Performance, IF = 100 MHz

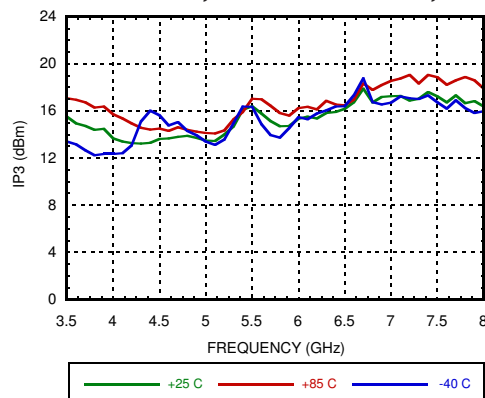
Conversion Loss vs. Temperature
LO = +13 dBm, RFIN = -10 dBm, LSB



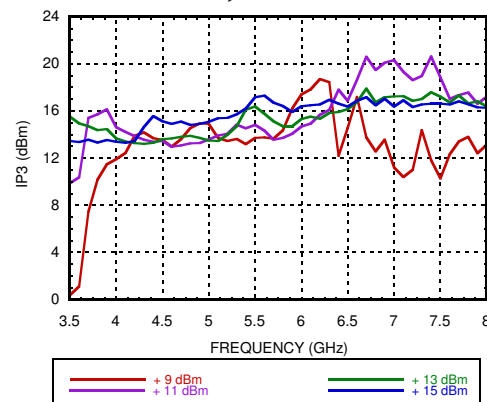
Conversion Loss vs. LO Drive
RFIN = -10 dBm, LSB



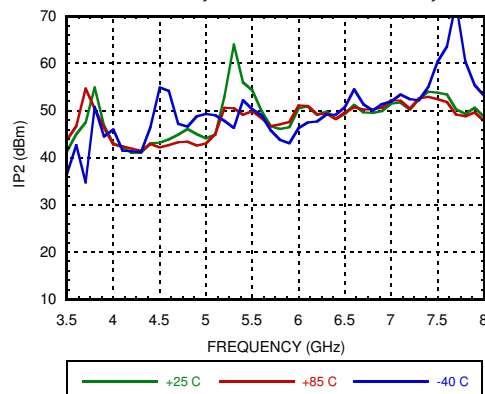
Input IP3 vs. Temperature
LO = +13 dBm, RFIN = -10 dBm, LSB



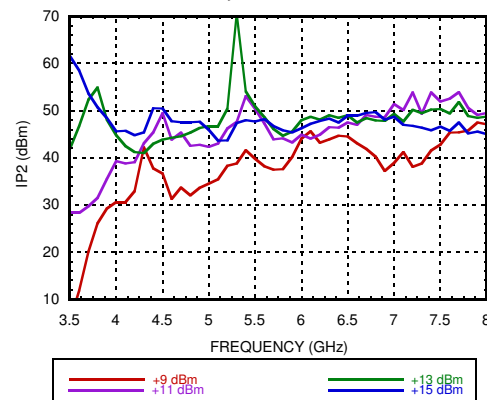
Input IP3 vs. LO Drive
RFIN = -10 dBm, LSB



Input IP2 vs. Temperature
LO = +13 dBm, RFIN = -10 dBm, LSB



Input IP2 vs. LO Drive
RFIN = -10 dBm, LSB

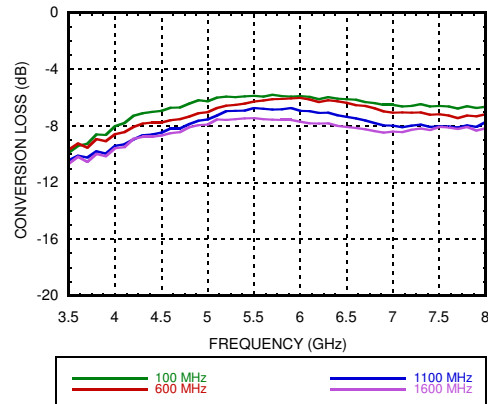


GaAs MMIC DOUBLE-BALANCED MIXER
3.5 - 8 GHz

High Side LO, Down-converter Performance, IF = 100 MHz

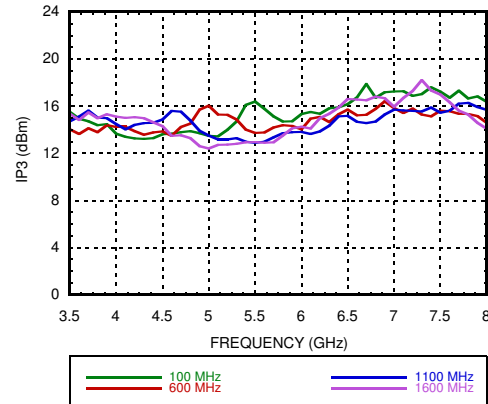
Conversion Loss vs. IF

LO = +13 dBm, RFIN = -10 dBm, LSB



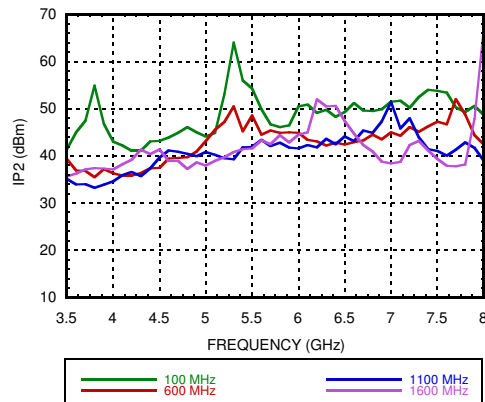
Input IP3 vs. IF

LO = +13 dBm, RFIN = -10 dBm, LSB



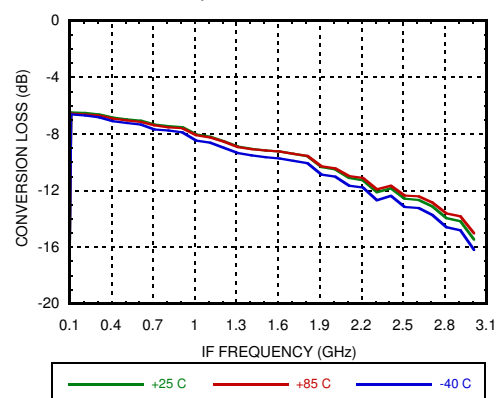
Input IP2 vs. IF

LO = +13 dBm, RFIN = -10 dBm, LSB



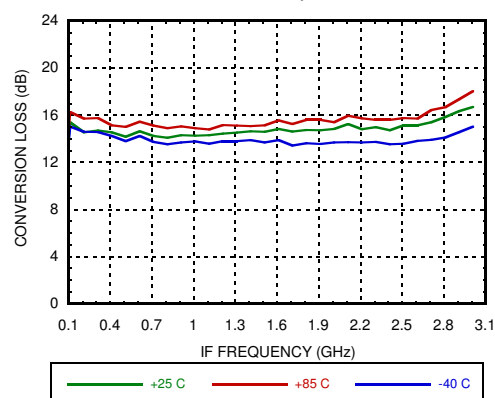
Conversion Loss over IF Bandwidth

@ LO = 6 GHz, LO Power = +13 dBm, LSB



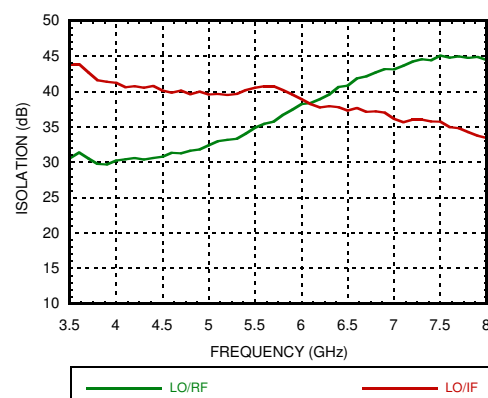
Input IP3 over IF Bandwidth, LO = 6 GHz

LO Power = +13 dBm, LSB



LO to RF and LO to IF Isolation

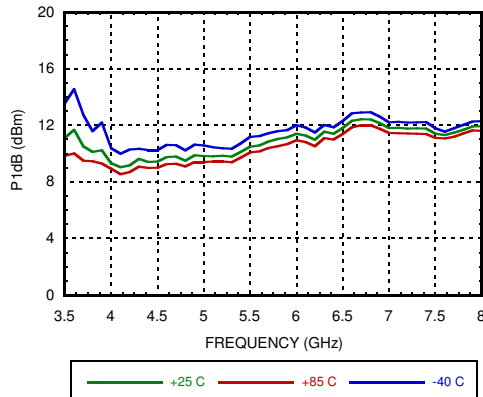
LO Power = +13 dBm



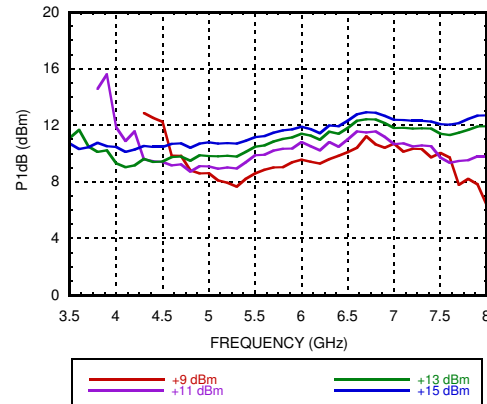
GaAs MMIC DOUBLE-BALANCED MIXER 3.5 - 8 GHz

High Side LO, Down-converter Performance, IF = 100 MHz

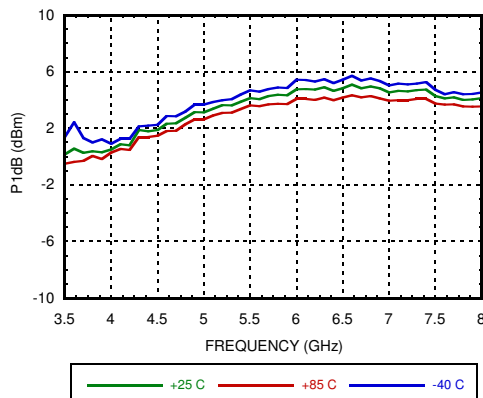
Input P1dB vs. Temperature
LO Power = +13 dBm, IF = 100 MHz



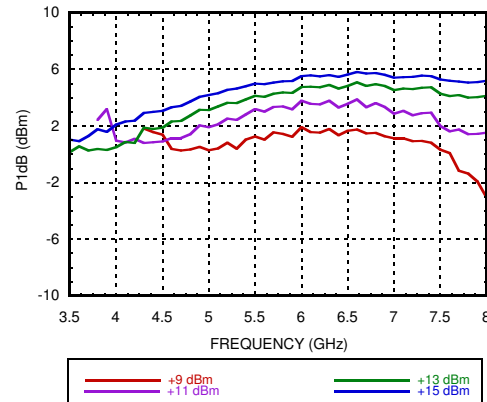
Input P1dB vs. LO Power
IF = 100 MHz,



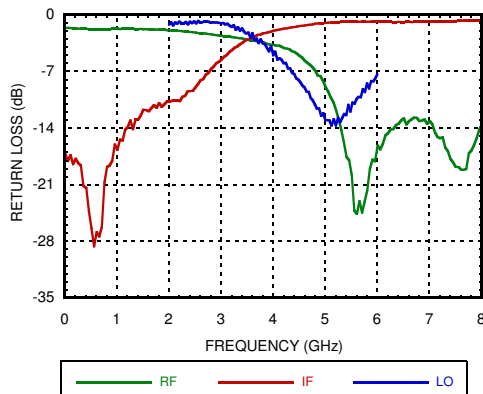
Output P1dB vs. Temperature
LO Power = +13 dBm, IF = 100 MHz



Output P1dB vs. LO Power
IF = 100 MHz



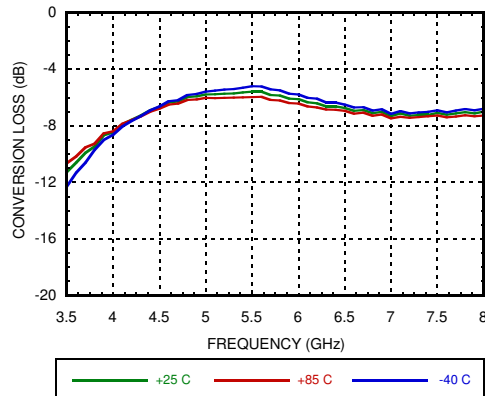
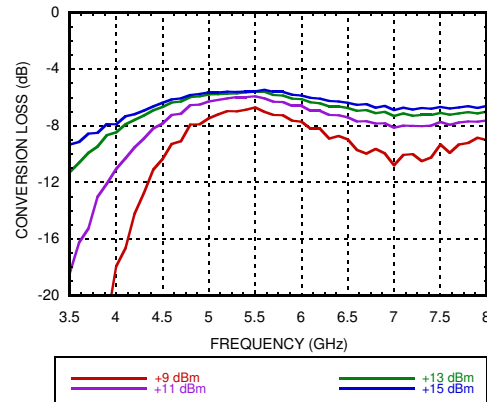
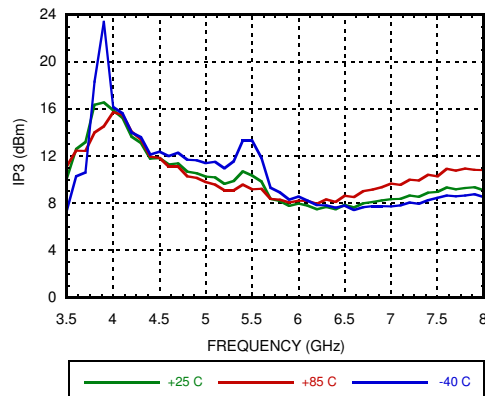
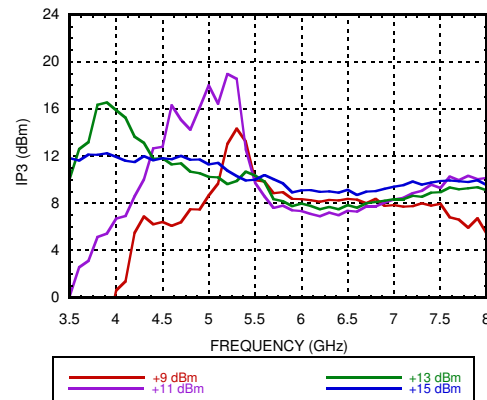
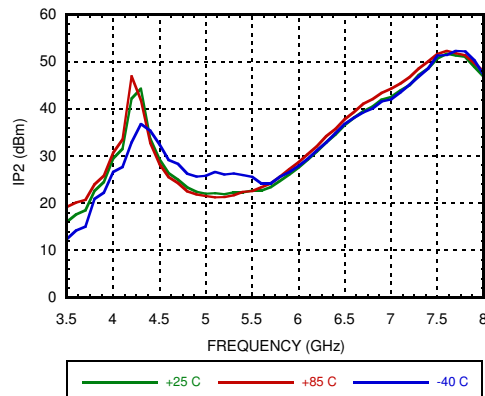
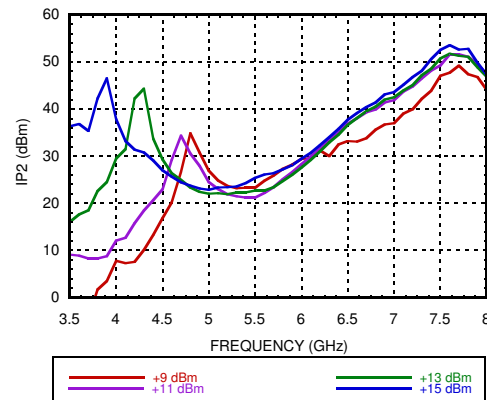
RF, LO, IF Return Loss @ LO = 4.6GHz
LO Power = +13 dBm



M x N Spurious Outputs, IF = 100 MHz

mRF	nLO					
	0	1	2	3	4	5
0		3.4	32.5	25.6	52.1	11.2
1	13.4		31.9	57.7	45.3	54.2
2	67.3	45.9	60.5	51.6	76.3	72.1
3	82.1	92.4	70.8	52	73.5	93.2
4	86.9	90.6	93.9	75.7	88.6	82.3
5	84	89.2	88.3	93.4	96	78.2

RF = 5.15 GHz @ -10 dBm
LO = 5.25 GHz @ +13 dBm
All values in dBc below IF power level (LO - RF) LSB
Spur values are (M x RF) - (N x LO)

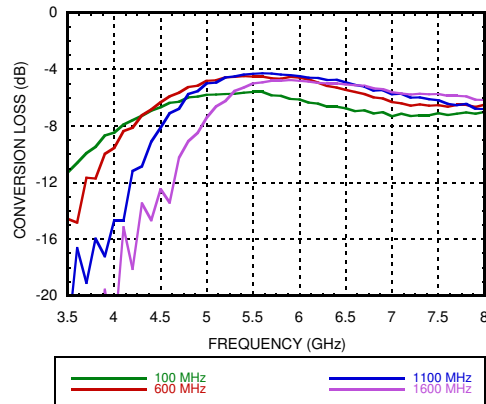
**GaAs MMIC DOUBLE-BALANCED MIXER
3.5 - 8 GHz**
Low Side LO, Up-converter Performance, IF = 100 MHz
Conversion Loss vs. Temperature
LO = +13 dBm, RFIN = -10 dBm, USB

Conversion Loss vs. LO Drive
RFIN = -10 dBm, USB

Input IP3 vs. Temperature
LO = +13 dBm, RFIN = -10 dBm, USB

Input IP3 vs. LO Drive
RFIN = -10 dBm, USB

Input IP2 vs. Temperature
LO = +13 dBm, RFIN = -10 dBm, USB

Input IP2 vs. LO Drive
RFIN = -10 dBm, USB


GaAs MMIC DOUBLE-BALANCED MIXER
3.5 - 8 GHz

Low Side LO, Up-converter Performance

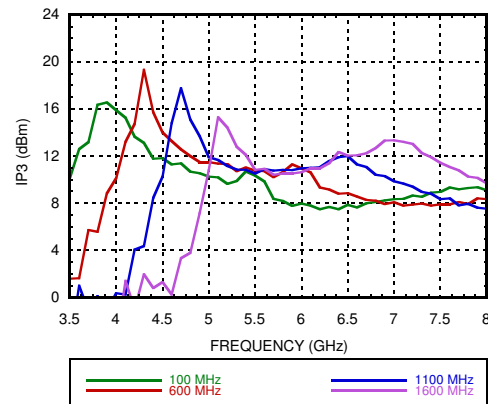
Conversion Loss vs. IF

LO = +13 dBm, RFIN = -10 dBm, USB



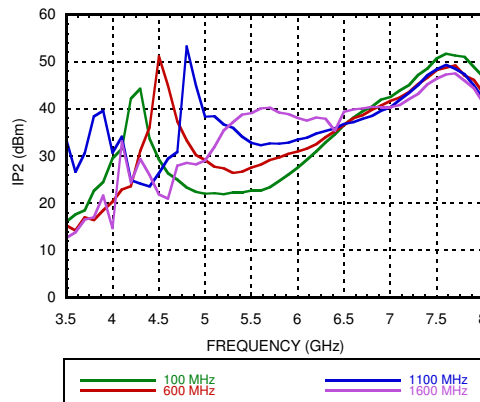
Input IP3 vs. IF

LO = +13 dBm, RFIN = -10 dBm, USB



Input IP2 vs. IF

LO = +13 dBm, RFIN = -10 dBm, USB



3,5 - 8 GHz

RF Power Input	+13 dBm
LO Power	+27 dBm
Channel Temperature	150 °C
Thermal Resistance (R _{TH}) (junction to ground paddle)	120 °C/W
Operating Temperature	-40°C to +85°C
Storage Temperature	-65°C to 150°C
ESD Sensitivity (HBM)	750 V (Class 1B)
ESD Sensitivity (CDM)	1000 V (Class C5)

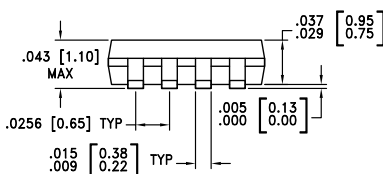
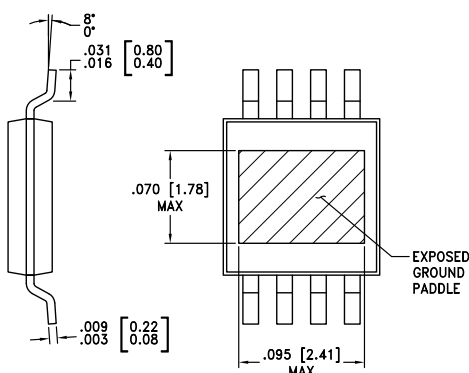
Mechanical drawing of the H218B component showing dimensions and tolerances. The drawing includes a central rectangular body with a circular feature on the left side. Dimensions are provided in inches with tolerances in brackets. A note indicates that the dimensions are for the component in its final state.

Dimensions and Tolerances:

- Top width: .122 [3.10 / 2.90]
- Top width (left side): .122 [3.10 / 2.90]
- Top width (right side): .200 [5.08 / 4.68]
- Bottom width: .122 [3.10 / 2.90]
- Bottom width (left side): .122 [3.10 / 2.90]
- Bottom width (right side): .200 [5.08 / 4.68]

Notes:

- LOT NUMBER
- 1
- 2
- 3
- 4



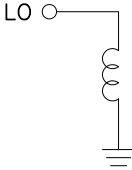
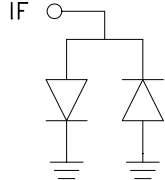
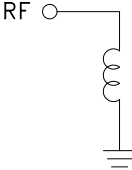
1. PACKAGE BODY MATERIAL: LOW STRESS INJECTION MOLDED PLASTIC. SILICA AND SILICON IMPREGNATED.
2. LEAD AND GROUND PADDLE MATERIAL: COPPER ALLOY
3. LEAD AND GROUND PADDLE PLATING: 100% MATTE TIN.
4. DIMENSIONS ARE IN INCHES [MILLIMETERS]
5. CHARACTERS TO BE HELVETICA MEDIUM, .030 HIGH, LASER OR WHITE INK,
LOCATED APPROXIMATELY AS SHOWN.
6. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
7. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
8. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.

Part Number	Package Body Material	Lead Finish	MSL Rating ^[2]	Package Marking ^[1]
HMC218BMS8GE	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1	<u>H218B</u> XXXX

[2] Max peak reflow temperature of 260 °C

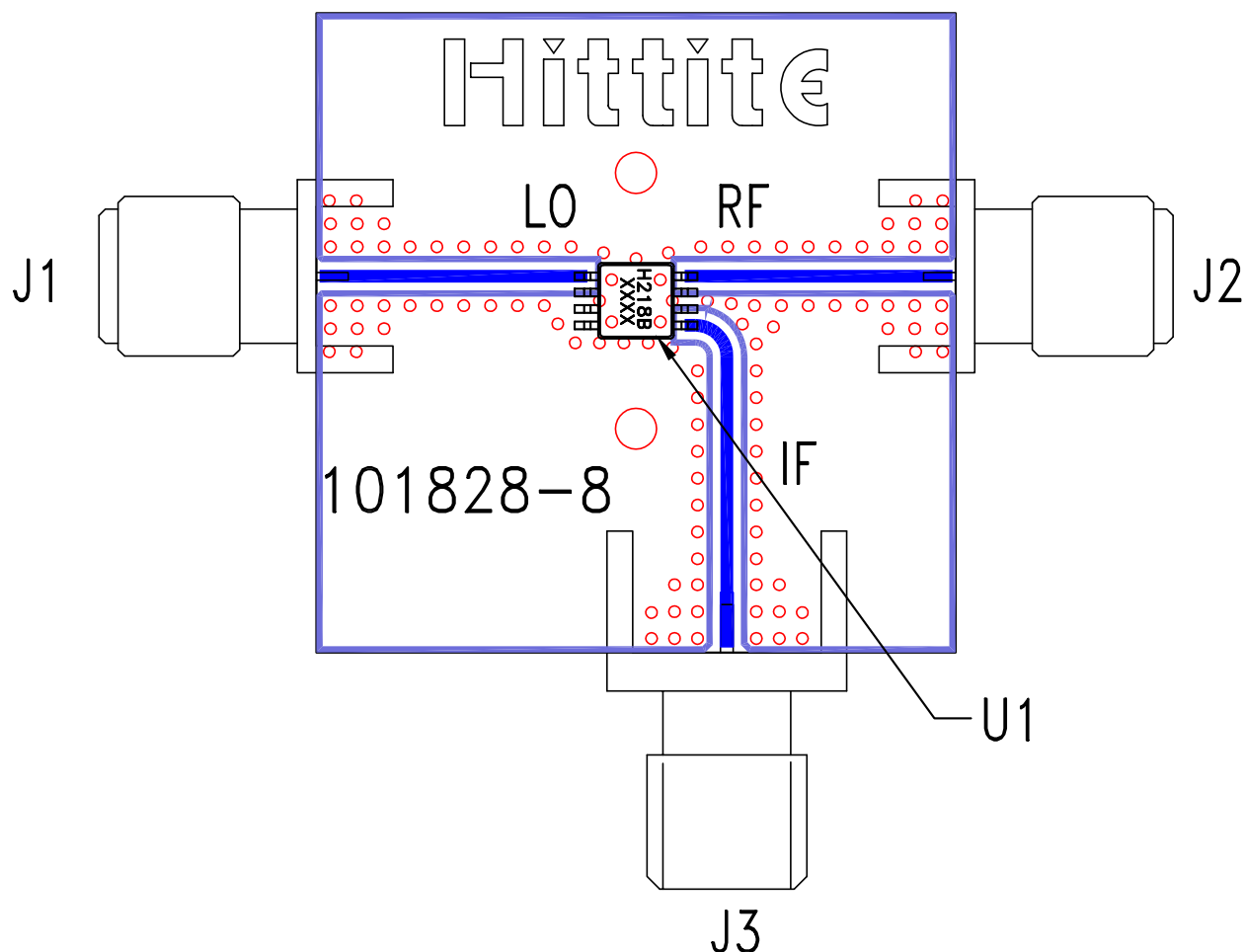
7

GaAs MMIC DOUBLE-BALANCED MIXER
3.5 - 8 GHz
Pin Descriptions

Pin Number	Function	Description	Pin Schematic
1	LO	This pin is DC coupled and matched to 50 Ohms.	
2, 3, 6, 7	GND	These pins and package bottom must be connected to RF/DC ground.	
4	N/C	No connected required. Pins are not connected internally. However, all data shown herein was measured with these pins connected to RF/DC ground internally.	
5	IF	This pin is DC coupled. For applications not requiring operation to DC, this port should be DC blocked externally using a series capacitor whose value has been chosen to pass the necessary IF frequency range. For operation to DC, this pin must not source or sink more than 2 mA of current or part non-function and possible part failure will result.	
8	RF	This pin is DC coupled and matched to 50 Ohms.	

GaAs MMIC DOUBLE-BALANCED MIXER
3.5 - 8 GHz

Evaluation PCB



List of Material for Evaluation PCB EV1HMC218BMS8G [1]

Item	Description
J1, J3	PCB Mount SMA RF Connector
U1	HMC218BMS8GE
PCB [2]	101828 Evaluation Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.

***GaAs MMIC DOUBLE-BALANCED MIXER
3.5 - 8 GHz*****Notes:**